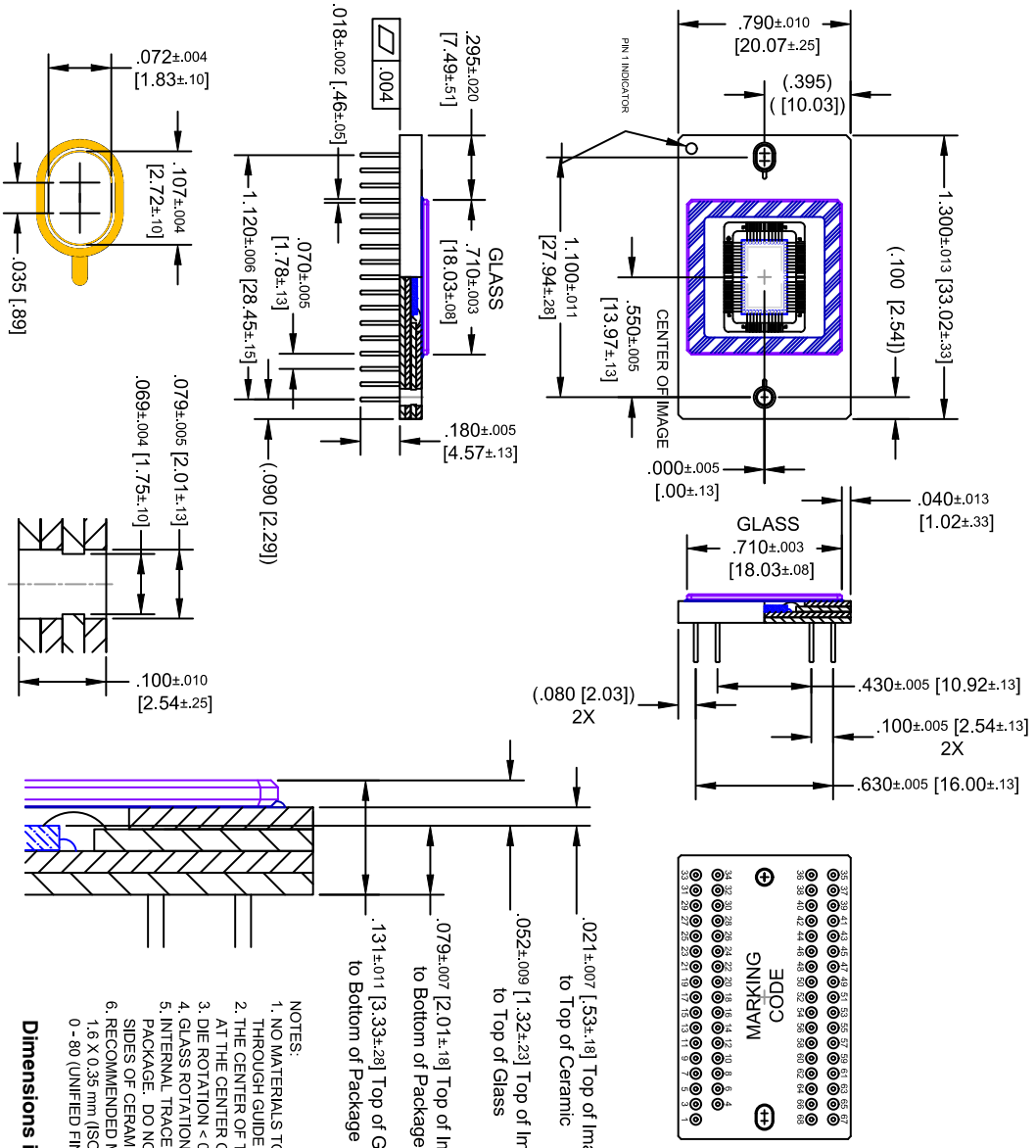
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

CPGA67, 33.02x20.07
CASE 107EL
ISSUE O

DATE 30 JUL 2014



NOTES:
1. NO MATERIALS TO INTERFERE WITH CLEARANCE THROUGH GUIDE HOLES.
2. THE CENTER OF THE ACTIVE IMAGE IS NOMINALLY AT THE CENTER OF THE PACKAGE.
3. DIE ROTATION < 0.5 DEGREES.
4. GLASS ROTATION < 1.5 DEGREES.
5. INTERNAL TRACES MAY BE EXPOSED ON SIDES OF PACKAGE. DO NOT ALLOW METAL TO CONTACT SIDES OF CERAMIC PACKAGE.
6. RECOMMENDED MOUNTING SCREWS:
1.6 X 0.35 mm (ISO STANDARD),
0 - 80 (UNIFIED FINE THREAD STANDARD).

Dimensions in: Inches [mm]

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